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40V DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

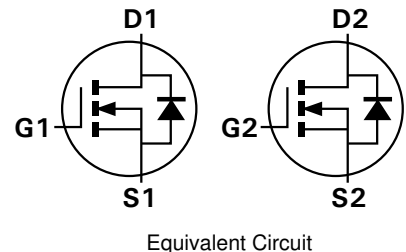
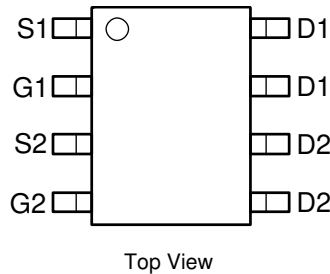
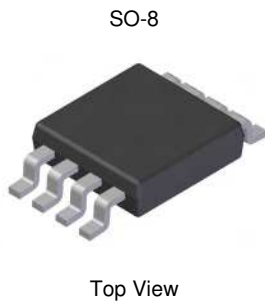
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = 25^\circ C$
40V	34mΩ @ $V_{GS} = 10V$	6.3A
	59mΩ @ $V_{GS} = 4.5V$	4.8A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor control
- Backlighting
- DC-DC Converters
- Power management functions



Features and Benefits

- 100% Unclamped Inductive Switch (UIS) test in production
- Low on-resistance
- Fast switching speed
- Max Q_g rated
- “Green” component and RoHS compliant (Note 1)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

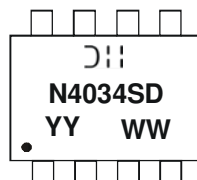
- Case: SO-8
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish - Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)

Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMN4034SSD-13	N4034SD	13	12	2,500

Notes: 1. Diodes, Inc. defines “Green” products as those which are RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.’s “Green” Policy can be found on our website. For packaging details, go to our website.

Marking Information



⌋:: = Manufacturer’s Marking
 N4034SD = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01 - 53)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

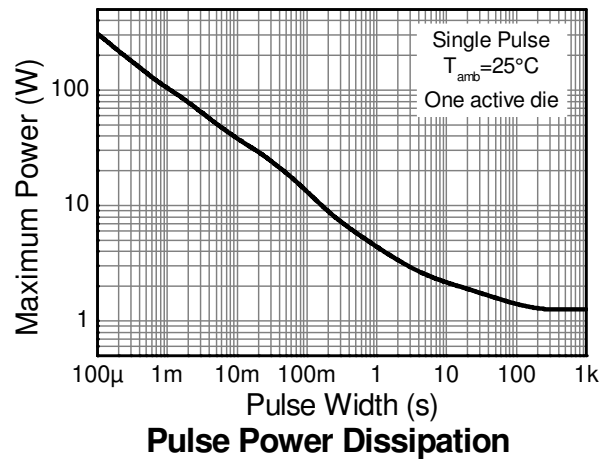
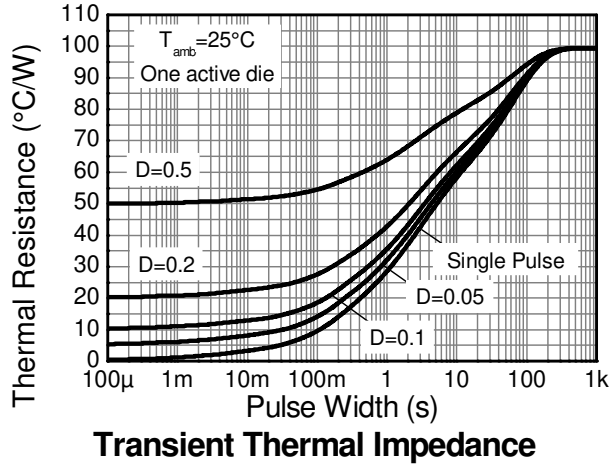
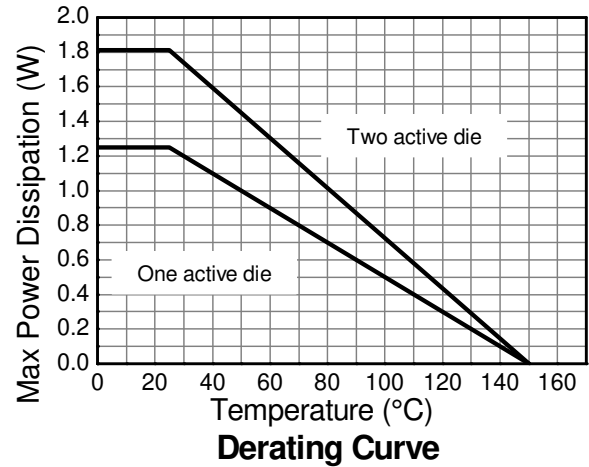
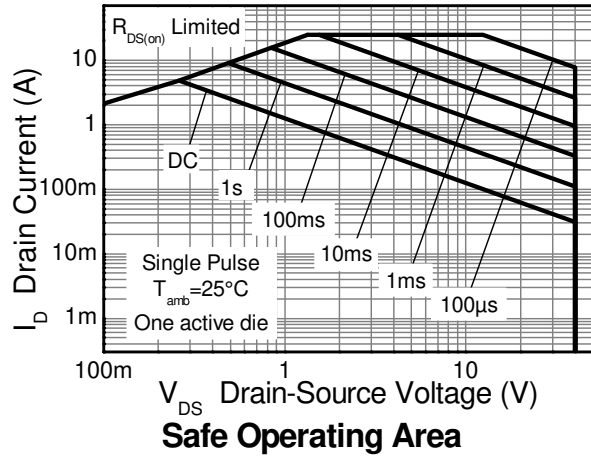
Characteristic			Symbol	Value	Unit
Drain-Source voltage			V_{DSS}	40	V
Gate-Source voltage		(Note 2)	V_{GS}	± 20	V
Single Pulsed Avalanche Energy			(Note 9)	E_{AS}	27
Single Pulsed Avalanche Current			(Note 9)	I_{AS}	15.25
Continuous Drain current	$V_{GS} = 10\text{V}$	(Note 4)	I_D	6.3	A
		$T_A = 70^\circ\text{C}$ (Note 4)		5.0	
		(Note 3)		4.8	
Pulsed Drain current	$V_{GS} = 10\text{V}$	(Note 5)	I_{DM}	24.8	A
Continuous Source current (Body diode)			(Note 4)	I_S	3.3
Pulsed Source current (Body diode)			(Note 5)	I_{SM}	24.8

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic		Symbol	Value	Unit
Power dissipation Linear derating factor	(Notes 3 & 6)	P_D	1.25	W mW/ $^\circ\text{C}$
	(Notes 3 & 7)		10.0	
	(Notes 4 & 6)		1.80	
	(Notes 4 & 6)		14.3	
Thermal Resistance, Junction to Ambient	(Notes 3 & 6)	$R_{\theta JA}$	2.14	$^\circ\text{C}/\text{W}$
	(Notes 3 & 7)		17.2	
	(Notes 4 & 6)		100	
Thermal Resistance, Junction to Lead	(Notes 6 & 8)	$R_{\theta JL}$	70	$^\circ\text{C}/\text{W}$
	(Notes 6 & 8)		58	
Operating and storage temperature range			T_J, T_{STG}	-55 to 150
				$^\circ\text{C}$

- Notes:
- AEC-Q101 V_{GS} maximum is $\pm 16\text{V}$.
 - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Same as note (3), except the device is measured at $t \leq 10$ sec.
 - Same as note (3), except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
 - For a dual device with one active die.
 - For a device with two active die running at equal power.
 - Thermal resistance from junction to solder-point (at the end of the drain lead).
 - UIS in production with $L = 100\mu\text{H}$, $V_{DD} = 40\text{V}$.

Thermal Characteristics

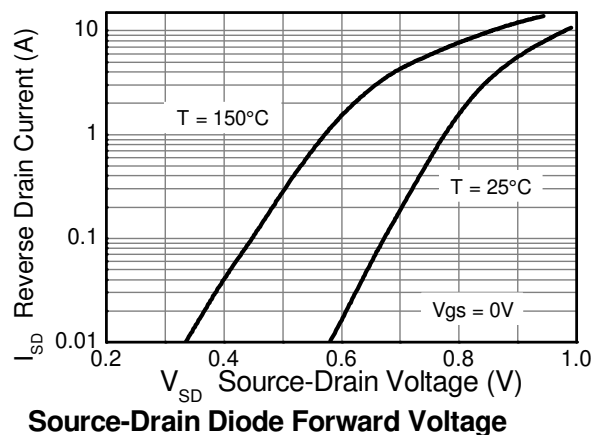
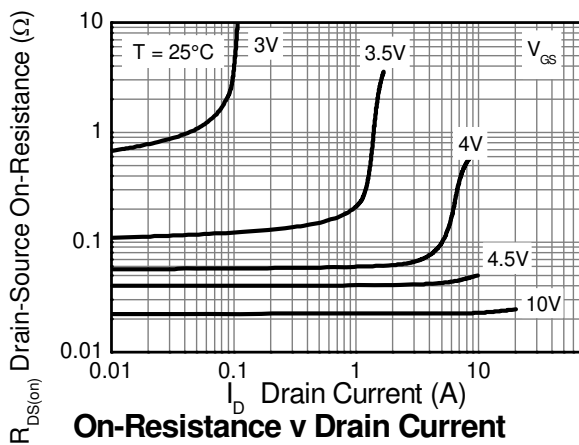
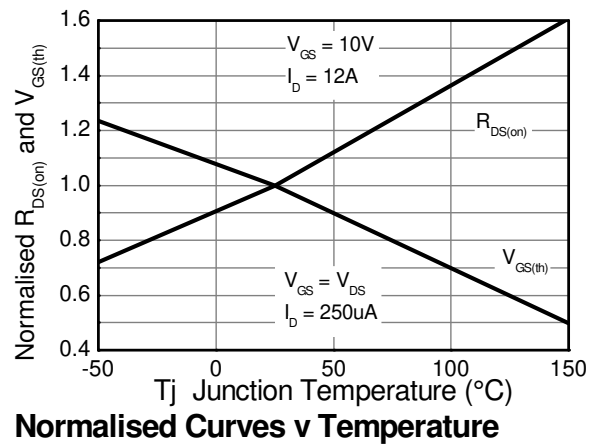
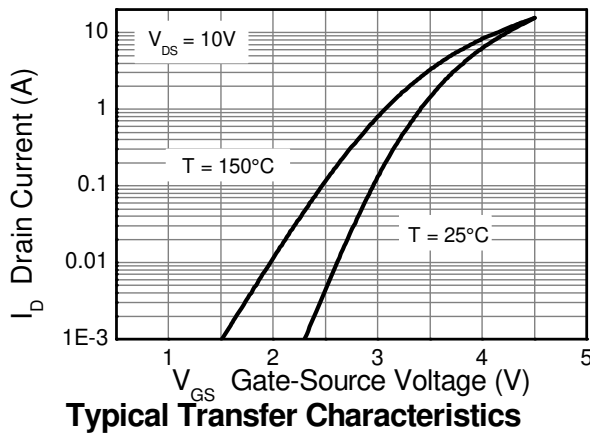
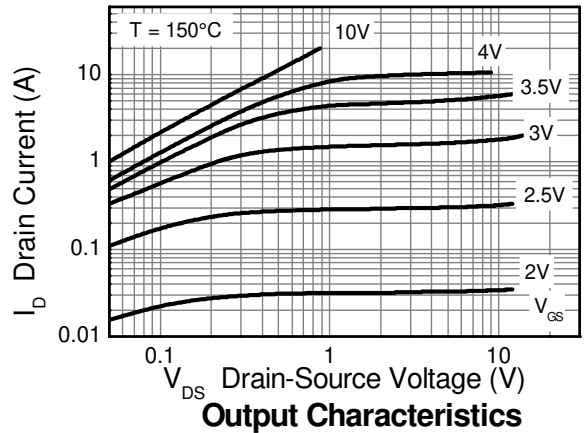
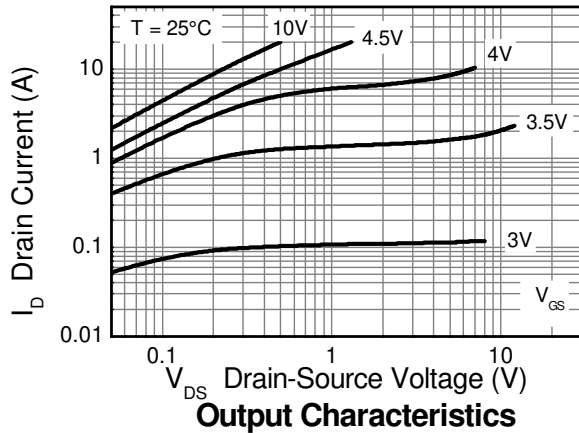


Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

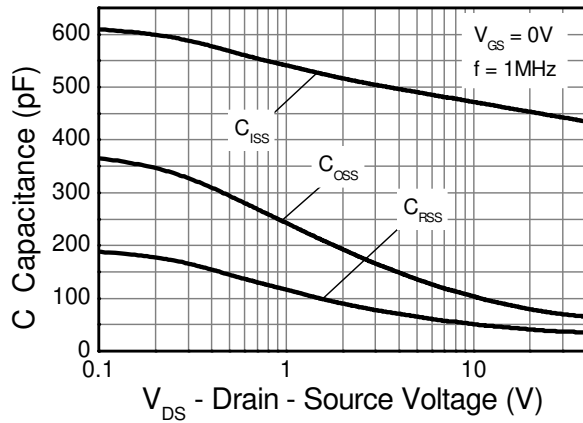
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	40	—	—	V	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 40\text{V}$, $V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	—	3.0	V	$I_D = 250\mu\text{A}$, $V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 10)	$R_{DS(on)}$	—	0.023	0.034	Ω	$V_{GS} = 10\text{V}$, $I_D = 6\text{A}$
			0.039	0.059		$V_{GS} = 4.5\text{V}$, $I_D = 5\text{A}$
Forward Transconductance (Notes 10 & 11)	g_{fs}	—	20.5	—	S	$V_{DS} = 15\text{V}$, $I_D = 6\text{A}$
Diode Forward Voltage (Note 10)	V_{SD}	—	0.87	1.1	V	$I_S = 6\text{A}$, $V_{GS} = 0\text{V}$
Reverse recovery time (Note 11)	t_{rr}	—	11.2	—	ns	$I_S = 2\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$
Reverse recovery charge (Note 11)	Q_{rr}	—	4.8	—	nC	
DYNAMIC CHARACTERISTICS (Note 11)						
Input Capacitance	C_{iss}	—	453	—	pF	$V_{DS} = 20\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	79.1	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	40.5	—	pF	
Total Gate Charge (Note 12)	Q_g	—	4.9	8	nC	$V_{GS} = 4.5\text{V}$
Total Gate Charge (Note 12)	Q_g	—	10	18	nC	$V_{GS} = 10\text{V}$
Gate-Source Charge (Note 12)	Q_{gs}	—	1.8	—	nC	
Gate-Drain Charge (Note 12)	Q_{gd}	—	2.4	—	nC	
Turn-On Delay Time (Note 12)	$t_{D(on)}$	—	2.7	—	ns	$V_{DD} = 20\text{V}$, $V_{GS} = 10\text{V}$ $I_D = 1\text{A}$, $R_G \cong 6.0\Omega$
Turn-On Rise Time (Note 12)	t_r	—	2.7	—	ns	
Turn-Off Delay Time (Note 12)	$t_{D(off)}$	—	14	—	ns	
Turn-Off Fall Time (Note 12)	t_f	—	6	—	ns	

Notes: 10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$
11. For design aid only, not subject to production testing.
12. Switching characteristics are independent of operating junction temperatures.

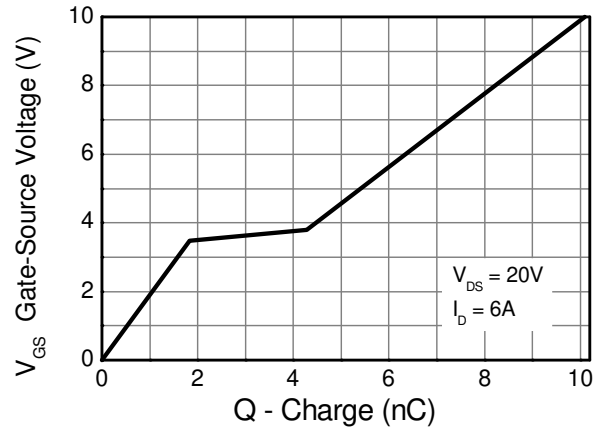
Typical Characteristics



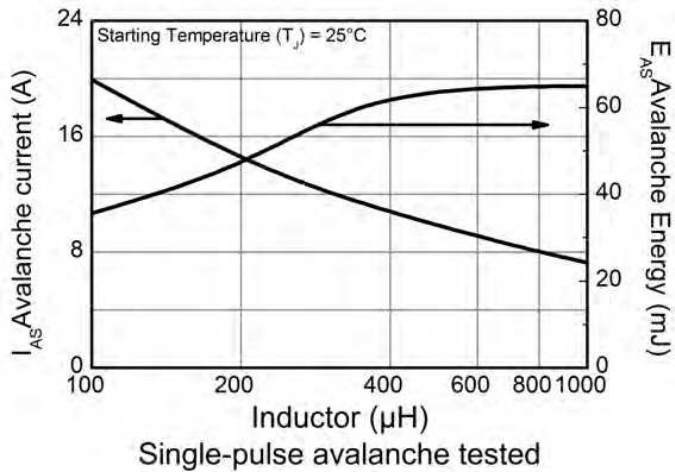
Typical Characteristics – continued



Capacitance v Drain-Source Voltage

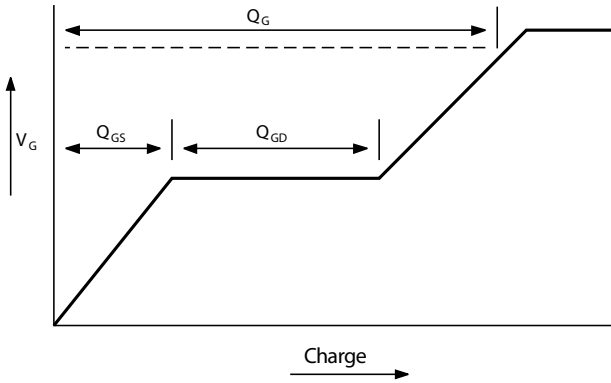


Gate-Source Voltage v Gate Charge

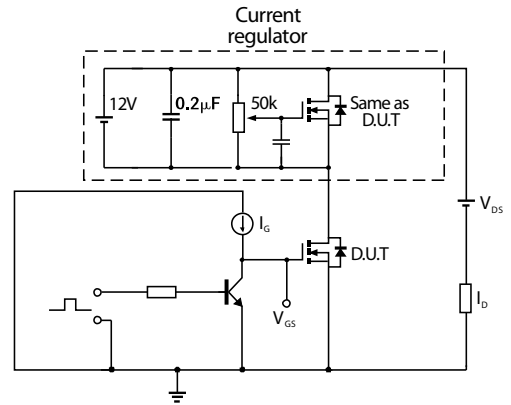


Single-pulse avalanche tested

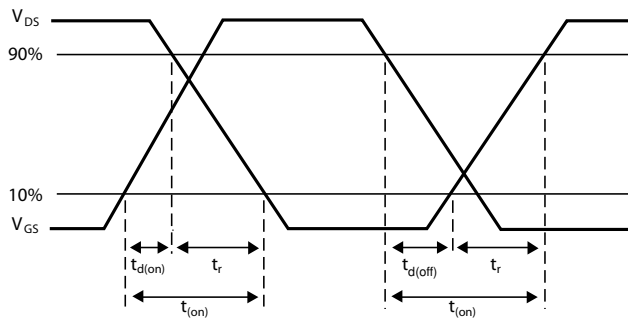
Test Circuits



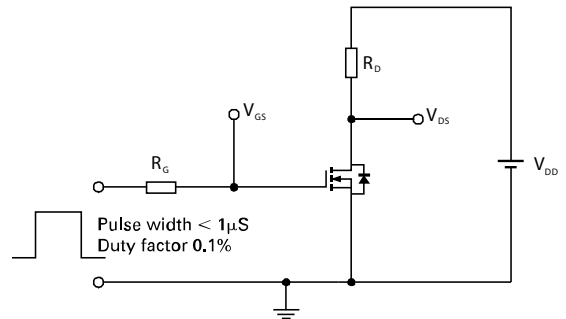
Basic gate charge waveform



Gate charge test circuit

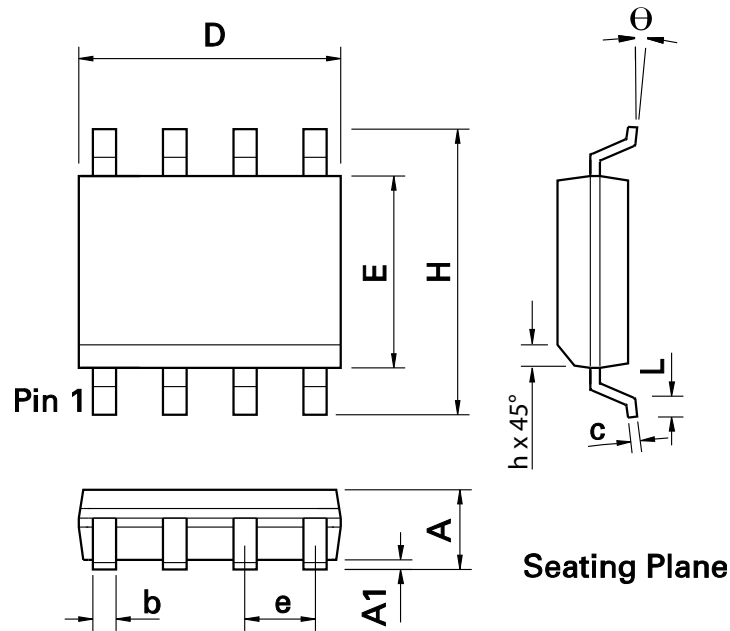


Switching time waveforms



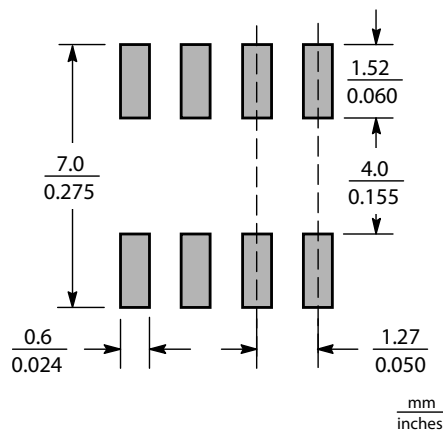
Switching time test circuit

Package Outline Dimensions



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.053	0.069	1.35	1.75	e	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25
H	0.228	0.244	5.80	6.20	theta	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

Suggested Pad Layout



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